

FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.  
MIC-24 Cont.APPLN. NO.  
10/644,278APPLICANT  
Kie Y. Ahn et al.CONF. NO.  
5174FILING DATE  
August 19, 2003GROUP ART UNIT  
1765INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
TTN	6,025,261	2/2000	Farrar et al.	438	619	
	6,083,802	7/2000	Wen et al.	438	381	
	6,107,893	8/2000	Forbes	331	132	
	6,191,468	2/2001	Forbes et al.	257	531	
	6,201,287	3/2001	Forbes	257	528	
	6,239,684	5/2001	Farrar et al.	336	200	
	6,240,622	6/2001	Ahn et al.	29	604	
	6,245,615	6/2001	Noble et al.	438	270	
	6,249,191	6/2001	Forbes	331	117FE	
	6,251,470	6/2001	Forbes et al.	427	97	
	6,277,728	8/2001	Ahn et al.	438	619	
	6,287,932	9/2001	Forbes et al.	438	381	
	6,414,550	7/2002	Forbes	330	264	
	6,420,954	7/2002	Ahn et al.	336	232	
	6,492,708	12/2002	Acosta et al.	257	531	
9	6,535,101	3/2003	Ahn et al.	336	232	
TTN	2003/0071325	4/2003	Xu et al.	257	531	

## FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

EXAMINER

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## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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TTN	Bassous, E., "Fabrication of Novel Three-Dimensional Microstructures by the Anisotropic Etching of (100) and (110) Silicon," <u>IEEE Transactions on Electron Devices</u> , vol. ED-25, no. 10, pp. 1178-85 (October 1978)
	Brodie, I., et al., <u>The Physics of Microfabrication</u> , pp. 1-78 (Plenum Press, New York 1982)
	Burghartz, J., et al., "Integrated RF and Microwave Components in BiCMOS Technology," <u>IEEE Transactions on Electron Devices</u> , vol. 43, no. 9, pp. 1559-70 (September 1996)
	Burghartz, J., et al., "Multilevel-Spiral Inductors Using VLSI Interconnect Technology," <u>IEEE Electron Device Letters</u> , vol. 17, no. 9, pp. 428-30 (September 1996)
	Chang, J.Y.-C., et al., "Large Suspended Inductors on Silicon and Their Use in a 2- $\mu$ m CMOS RF Amplifier," <u>IEEE Electron Device Letters</u> , vol. 14, no. 5, pp. 246-48 (May 1993)
	Frye, R.C., et al., "Inductive Crosstalk Between Integrated Passive Components in RF-Wireless Modules," <u>IEEE Proceedings of the 1998 International Conference on Multichip Modules and High Density Packaging</u> , pp. 496-500 (1998)
TTN	Pieters, P., et al., "Spiral Inductors Integrated in MCM-D using the Design Space Concept," <u>IEEE Proceedings of the 1998 International Conference on Multichip Modules and High Density Packaging</u> , pp. 478-83 (1998)

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